
Integrirana vezja - Meritve elektromagnetne odpornosti - 2. del: Meritev odpornosti proti sevanju - Metoda s celico TEM in širokopasovno celico TEM (IEC 62132-2:2010)

Integrated circuits - Measurement of electromagnetic immunity - Part 2: Measurement of radiated immunity - TEM cell and wideband TEM cell method (IEC 62132-2:2010)

Integrierte Schaltungen - Messung der elektromagnetischen Störfestigkeit - Teil 2: Messung der Störfestigkeit bei Einstrahlungen - TEM-Zellen- und Breitband-TEMZellenverfahren (IEC 62132-2:2010)

Circuits intégrés - Mesure de l'immunité électromagnétique - Partie 2: Mesure de l'immunité rayonnée - Méthode de cellule TEM et cellule TEM à large bande (CEI 62132-2:2010)

Ta slovenski standard je istoveten z: EN 62132-2:2011

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EUROPEAN STANDARD
NORME EUROPÉENNE
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EN 62132-2

March 2011

ICS 31.200

English version

**Integrated circuits -
Measurement of electromagnetic immunity -
Part 2: Measurement of radiated immunity -
TEM cell and wideband TEM cell method
(IEC 62132-2:2010)**

Circuits intégrés -
Mesure de l'immunité électromagnétique -
Partie 2: Mesure de l'immunité rayonnée -
Méthode de cellule TEM et cellule TEM à
large bande
(CEI 62132-2:2010)

Integrierte Schaltungen -
Messung der elektromagnetischen
Störfestigkeit -
Teil 2: Messung der Störfestigkeit bei
Einstrahlungen -
TEM-Zellen- und Breitband-TEM-
Zellenverfahren
(IEC 62132-2:2010)

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CENELEC

European Committee for Electrotechnical Standardization
Comité Européen de Normalisation Electrotechnique
Europäisches Komitee für Elektrotechnische Normung

Management Centre: Avenue Marnix 17, B - 1000 Brussels

Foreword

The text of document 47A/838/FDIS, future edition 1 of IEC 62132-2, prepared by SC 47A, Integrated circuits, of IEC TC 47, Semiconductor devices, was submitted to the IEC-CENELEC parallel vote and was approved by CENELEC as EN 62132-2 on 2011-01-02.

This part of EN 62132 is to be read in conjunction with EN 62132-1.

Attention is drawn to the possibility that some of the elements of this document may be the subject of patent rights. CEN and CENELEC shall not be held responsible for identifying any or all such patent rights.

The following dates were fixed:

- | | | |
|--|-------|------------|
| – latest date by which the EN has to be implemented at national level by publication of an identical national standard or by endorsement | (dop) | 2011-10-02 |
| – latest date by which the national standards conflicting with the EN have to be withdrawn | (dow) | 2014-01-02 |

Annex ZA has been added by CENELEC.

Endorsement notice

The text of the International Standard IEC 62132-2:2010 was approved by CENELEC as a European Standard without any modification.

In the official version, for Bibliography, the following notes have to be added for the standards indicated:

- | | |
|----------------------------|--|
| [7] IEC 61000-4-3:2006 | NOTE Harmonized as EN 61000-4-3:2006 (not modified). |
| IEC 61000-4-3:2006/A1:2007 | NOTE Harmonized as EN 61000-4-3:2006/A1:2008 (not modified). |
| [8] IEC 61000-4-6:2008 | NOTE Harmonized as EN 61000-4-6:2009 (not modified). |
| [9] IEC 61000-4-20:2003 | NOTE Harmonized as EN 61000-4-20:2003 (not modified). |
| [10] CISPR 16-1-1:2006 | NOTE Harmonized as EN 55016-1-1:2007 (not modified). |
| [12] CISPR 16-1-5:2003 | NOTE Harmonized as EN 55016-1-5:2004 (not modified). |
| [13] CISPR 16-2-1:2008 | NOTE Harmonized as EN 55016-2-1:2009 (not modified). |
| [15] CISPR 16-2-3:2006 | NOTE Harmonized as EN 55016-2-3:2006 (not modified). |
| [16] CISPR 16-2-4:2003 | NOTE Harmonized as EN 55016-2-4:2004 (not modified). |

Annex ZA (normative)

Normative references to international publications with their corresponding European publications

The following referenced documents are indispensable for the application of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

NOTE When an international publication has been modified by common modifications, indicated by (mod), the relevant EN/HD applies.

<u>Publication</u>	<u>Year</u>	<u>Title</u>	<u>EN/HD</u>	<u>Year</u>
IEC 60050-131	2002	International Electrotechnical Vocabulary (IEV) - Part 131: Circuit theory	-	-
IEC 60050-161	1990	International Electrotechnical Vocabulary (IEV) - Chapter 161: Electromagnetic compatibility	-	-
IEC 61967-2	-	Integrated circuits - Measurement of electromagnetic emissions, 150 kHz to 1 GHz - Part 2: Measurement of radiated emissions - TEM cell and wideband TEM cell method	EN 61967-2	-
IEC 62132-1	2006	Integrated circuits - Measurement of electromagnetic immunity, 150 kHz to 1 GHz - Part 1: General conditions and definitions	EN 62132-1 + corr. November	2006 2006

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INTERNATIONAL STANDARD

NORME INTERNATIONALE

**Integrated circuits – Measurement of electromagnetic immunity –
Part 2: Measurement of radiated immunity – TEM cell and wideband TEM cell
method**

**Circuits intégrés – Mesure de l'immunité électromagnétique –
Partie 2: Mesure de l'immunité rayonnée – Méthode de cellule TEM et cellule
TEM à large bande**

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INTERNATIONAL ELECTROTECHNICAL COMMISSION

**INTEGRATED CIRCUITS – MEASUREMENT OF
ELECTROMAGNETIC IMMUNITY –****Part 2: Measurement of radiated immunity –
TEM cell and wideband TEM cell method**

FOREWORD

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International Standard IEC 62132-2 has been prepared by subcommittee 47A: Integrated circuits, of IEC technical committee 47: Semiconductor devices.

The text of this standard is based on the following documents:

FDIS	Report on voting
47A/838/FDIS	47A/843/RVD

Full information on the voting for the approval of this standard can be found in the report on voting indicated in the above table.

This publication has been drafted in accordance with the ISO/IEC Directives, Part 2.

This part of IEC 62132 is to be read in conjunction with IEC 62132-1.

The committee has decided that the contents of this publication will remain unchanged until the stability date indicated on the IEC web site under "<http://webstore.iec.ch>" in the data related to the specific publication. At this date, the publication will be

- reconfirmed,
- withdrawn,
- replaced by a revised edition, or
- amended.

Future standards in this series will carry the new general title as cited above. Titles of existing standards in this series will be updated at the time of the next edition.

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INTEGRATED CIRCUITS – MEASUREMENT OF ELECTROMAGNETIC IMMUNITY –

Part 2: Measurement of radiated immunity – TEM cell and wideband TEM cell method

1 Scope

This International Standard specifies a method for measuring the immunity of an integrated circuit (IC) to radio frequency (RF) radiated electromagnetic disturbances. The frequency range of this method is from 150 kHz to 1 GHz, or as limited by the characteristics of the TEM cell.

2 Normative references

The following referenced documents are indispensable for the application of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

IEC 60050-131:2002, *International Electrotechnical Vocabulary (IEV) – Part 131: Circuit theory*

IEC 60050-161:1990, *International Electrotechnical Vocabulary (IEV) – Chapter 161: Electromagnetic compatibility*

IEC 61967-2, *Integrated circuits – Measurement of electromagnetic emissions, 150 kHz to 1 GHz – Part 2: Measurement of radiated emissions – TEM cell and wideband TEM cell method*

IEC 62132-1:2006, *Integrated circuits – Measurement of electromagnetic immunity, 150 kHz to 1 GHz – Part 1: General conditions and definitions*

3 Terms and definitions

For the purpose of this document, the definitions in IEC 62132-1, IEC 60050-131 and IEC 60050-161, as well as the following, apply.

3.1

transverse electromagnetic mode (TEM)

waveguide mode in which the components of the electric and magnetic fields in the propagation direction are much less than the primary field components across any transverse cross-section

3.2

TEM waveguide

open or closed transmission line system, in which a wave is propagating in the transverse electromagnetic mode to produce a specified field for testing purposes.